

ZESTRON® SD 301

Cleaning medium for the removal of solder pastes, SMT adhesives and thick film pastes from stencils and screens



ZESTRON® SD 301 is an improved version of ZESTRON® SD 300 with a lower odor. Especially a faster drying time allows for shorter cleaning processes. The solvent-based cleaner removes solder pastes, SMT adhesives as well as thick film pastes from stencils and screens in spray-in-air systems. Its high flash point permits both manual use and the application in printers and stencil cleaning equipment.

Areas of application:		Additional product information:
Stencils and screens		Technical Information 2: Overview of all fluxes and solder pastes tested
Solder paste (unsoldered)	++	
SMT or conductive adhesives	++	
Thick film pastes	++	Technical Information 3: Material compatibility overview
Misprinted board cleaning		
Low solid flux residues	0	Application Recommendation: Specific process parameter for your cleaning trial
Rosin-based flux residues	+	
Water soluble flux residues	0	

++ highly recommended, best results + recommended 0 possible - not recommended

Technical Centers - ① America, ② Europe, ③ Malaysia, ④ North-China, ⑤ South-China
Cleaning Process Solutions under Production Floor Conditions



Contact ZESTRON's Process Engineering Team for free-of-charge cleaning trials:
 Phone: +49-841-635-26; Email: techsupport@zestron.com

Advantages compared to other cleaners:

- Due to its wide process window, ZESTRON® SD 301 reliably removes solder pastes, SMT adhesives and resistor pastes from stencils and screens as well as flux residues from misprinted assemblies.
- High loading capabilities, long bath life and therefore low cleaning costs.
- ZESTRON® SD 301 has a high flash point of 47° C / 117° F and can be used without external explosion-protection systems.
- Has a short overall process time.
- The cleaning medium is based on non-halogenated, organic solvents.
- Applicable at ambient cleaning temperature.
- Low odor as well as fast drying time.


Please refer to the material compatibility list (Technical Information 3) before cleaning plastics.

ZESTRON® SD 301 is approved by leading international cleaning equipment manufacturers. Written approvals can be obtained from ZESTRON.


Process Steps	1. Cleaning	2. Rinsing	3. Drying
Explosion-proof spray-in-air-system	ZESTRON® SD 301	ZESTRON® SD 301	Circulating or compressed air

Technical Data		
Density	(g/ccm) at 20°C/68°C	0.88
Surface tension	(mN/m) at 25°C/77°F	26.0
Boiling range	°C/°F	150 – 170 / 302 – 338
Flash point	°C/°F	47 / 117
pH-value	10g/l H ₂ O	Neutral
Vapor pressure	(mbar) bei 20°C/68°F	2
Cleaning temperature	°C/°F	Room temperature
Solubility in water		Soluble
Application concentration	Ready-to-use	Pure
HMIS Rating	Health-Flammability-Reactivity	1 – 2 – 0


PRODUCT FEATURES



Extensively tested and suitable for cleaning of lead-free solder pastes



Product is free of any critical substances according to SIN & SVHC lists



100% compliance with EU guidelines (RoHS 1 & 2, WEEE)

Filter recommendation:

- To further improve the long bath life time of ZESTRON® SD 301, filtration is recommended.
- For details, please request our “Filter Recommendation” sheet.

Environmental, health and safety regulations:

- ZESTRON® SD 301 is formulated free of any halogenated compounds and is biodegradable.
- Water rinsing is not necessary which results in the elimination of waste water concerns.
- Refer to the MSDS for specific handling precautions and instructions.

Availability/Storage:

- ZESTRON® SD 301 is available in 1l bottles, 5l or 25l containers and 200l drums.
- Store ZESTRON® SD 301 in the original container at a temperature between 5 - 30°C / 41 - 86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.

Alternative product recommendation:

- For the water-based cleaning of stencils, we recommend the MPC® based product VIGON® SC 200.